

ABSTRACT

A method and an apparatus for resin-sealing and resin-molding an electronic component, capable of reliably preventing formation of a void within a molded package, are provided. The resin-sealing and resin-molding apparatus includes a first die (111), a second die (112), a pot block (140), and a pressure reduction mechanism. The first die (111) has a first die surface, and a substrate (400) on which the electronic component is mounted is attached to the first die. The second die (112) has a second die surface opposed to the first die surface and a cavity (114) receiving the electronic component. The pot block (140) injects a resin material through a gap while the first die (111) and the second die (112) are fastened to each other. When the resin material is injected, the pressure reduction mechanism produces vacuum in a space formed between the first die surface, the second die surface, and the pot block (140).